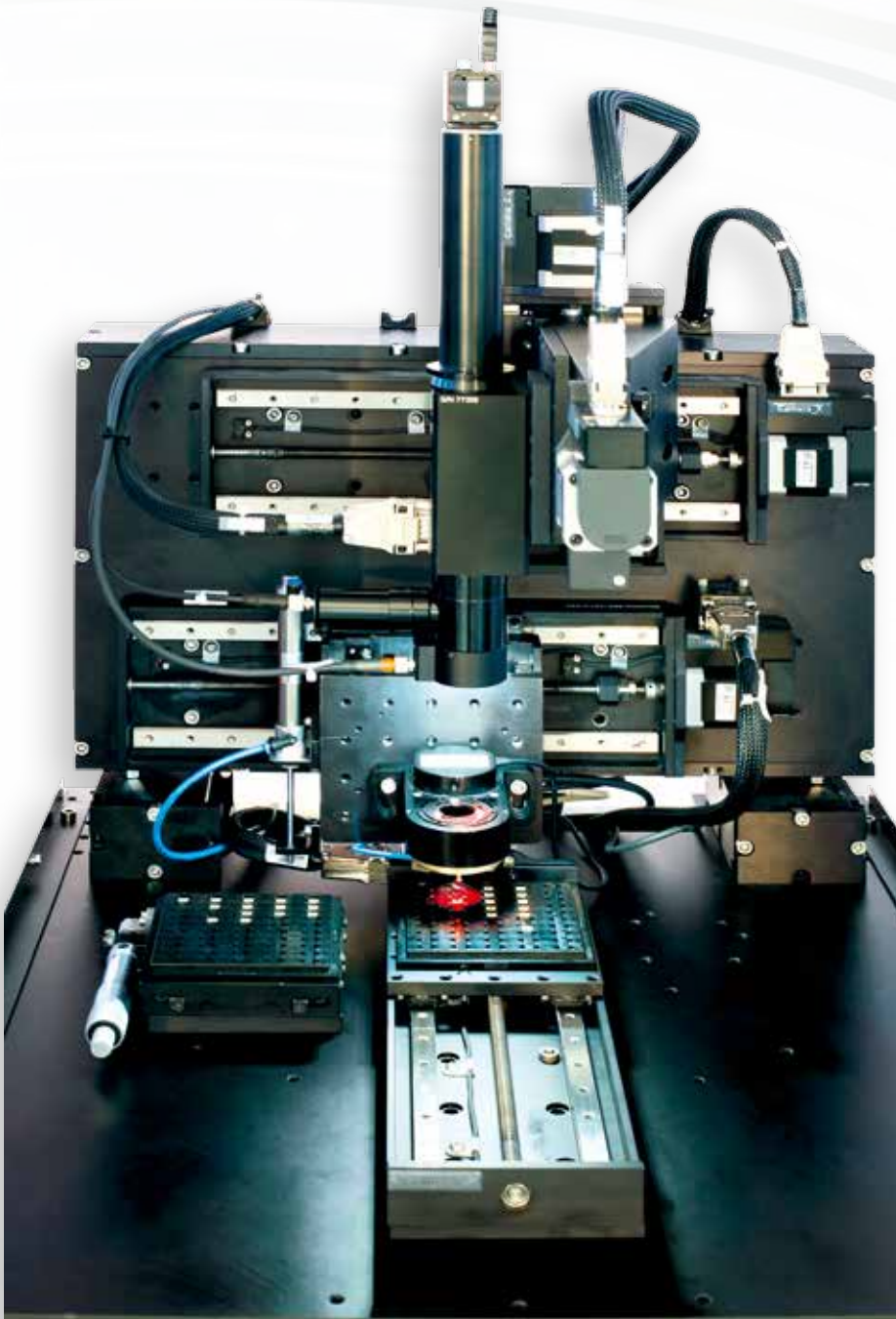


NanoPlace

High-Precision Micro Assembly Station with
Epoxy Gluing or Laser Soldering

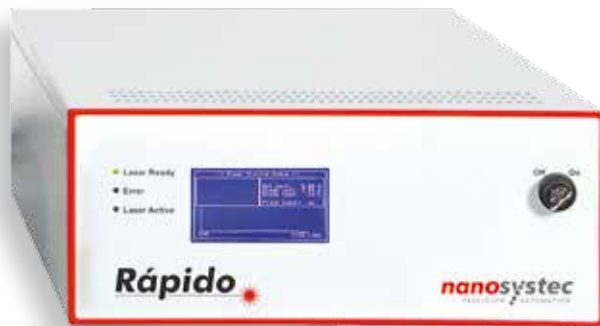


NanoPlace

Precision Assembly for Medium Volume

The fully automated assembly station NanoPlace covers a work area of 200 mm x 200 mm (other dimensions on request). It takes components, such as lenses or dies from a loading area and mounts them onto carrier devices. The assembly methods include epoxy gluing with UV or thermal curing as well as laser soldering.

The station covers low to medium volume with the same performance as larger systems, but at a reasonable price.



The laser system Rápido is a 19 in. rack mount unit.

Pick-Up with 360° Capability

The devices to be mounted are picked up from a custom loading jig or directly from a wafer or Gel-Pak. The pickup tool is centered underneath a rotational stage with a large aperture. The machine vision system recognizes the orientation of the device and brings the gripping tool into the correct rotational position for the placement. A preorientation of the components is not necessary.

While the assembly process runs automated, the loading of the cassettes and jigs with the components to be assembled and the unloading of the finished devices remain a manual operation.

Gripping with Optional Force Detection

In the standard version, a vacuum gripper is used. Different sizes of the devices to be picked are addressed with various sizes and shapes of the tips. Alternatively, standard pick-up tools for semiconductor applications can be used. An optional force measurement allows for applying a repeatable pressure during the bonding procedure.

Repeatable Positioning

Thorough design and continuous optimization of all functional groups lead to superior mechanical stability. Mechanical references with tight tolerances provide a repeatable manufacturing operation from device to device.

The pick-and-place motion system consists of high-precision motion stages with crossed-roller bearings. They are equipped with brushless DC servo motors with position feedback for repeatable high-velocity positioning in the micrometer regime.

The camera system moves independently from the pick-and-place motion stack and carries the syringe or epoxy stamping tool for the resin or the laser soldering optics. This assembly also holds the UV lamps or the light guides.

The motion stages are mounted onto a vibration-isolated structure. This solid set-up makes NanoPlace insensitive against disturbing external influences and provides a high stability during the assembly procedure.

Benefits of NanoPlace

- High-precision station
- Medium volume at reasonable price
- Pick-up with 360° capability
- Repeatable positioning
- Motorized zoom lens with factor 12.5
- LED illumination in various colors



Powerful Machine Vision Capability

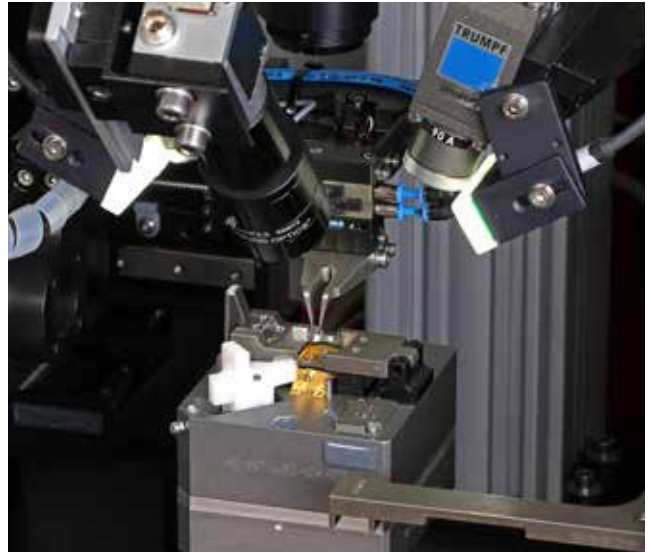
The NanoPlace Stations use automated machine vision algorithms. These include pattern recognition, object detection, edge detection and autofocus. The parts and features on the devices are automatically detected which allows for a repeatable gripping position.

Motorized Zoom Function

A motorized zoom lens with a factor of 12.5 identifies positions with an uncertainty of several micrometers in the high magnification while in the low magnification a large field of view is displayed. The low magnification is used to see the various nests and detect their occupation while the high magnification delivers a precision view for pick-up and placement.

Adjustable Illumination in various Colors

Various brightness settings of the LED illumination provide ideal imaging conditions. Different colors help to identify even difficult surfaces and features which are hard to see. Standard illumination consists of coaxial lighting through the lens, a ring light from top and side-mounted LEDs with diffusers.



Cameras mounted to the focusing lenses of the laser processing optics support the image data processing during laser soldering and laser welding. In addition, machine vision monitors the dispensing of resin or solder paste.

Epoxy Gluing or Laser Soldering Capability

For the final assembly, the NanoPlace station is either equipped with epoxy gluing with subsequent UV/thermal curing or with laser soldering capability.

Epoxy Gluing. The epoxy is applied with a dispenser or with a stamping tool. The machine vision system monitors this procedure. After the epoxy is applied and the component is in place, UV guides or UV-LEDs are shuttled into position for the curing procedure.

The syringes of the dispenser or the stamping tool are mounted to the motion system of the camera which moves independently from the pick-and-place stages. They are mounted in a way that the camera monitors the application of the resin.

Laser Soldering. If solder paste or a preform is used, a high power diode laser locally heats the solder to a precise temperature with minimal heat impact to the surrounding area.

As an option, the patented multi-spot beam optics form a geometric pattern of several spots which are treated at the same time. This method avoids tombstone effects and increases the throughput.

A second camera which is mounted to the laser head allows for precise view through the soldering lens assembly in order to automate this process step.



Various assembly techniques can be combined in one station, such as laser welding, laser soldering and epoxy gluing. Exchangeable device trays allow for the versatile micro assembly in various batch processes.

Process Software

The automated processes run based on TestMaster process software. This software works with a direct user interface for teaching positions and adapting the process parameters.

The automated process flow is programmed in the YASE sequence editor. The customer has full access rights to this programming and can modify the processes as required.

This structure provides a smooth and secure operation of the systems in high technology production environments.



Multiple device trays and stop-motion conveyor belts increase the throughput and allow for the integration into fully automated production lines.

Process Monitoring

Digital inputs on the general machine control or on the motion controller are permanently monitored and can be displayed. Depending on the process, automated actions follow when a certain interlock or emergency function changes the status. Also a possible power, pressure or vacuum outage can be detected. An automated shut-down can be executed depending on the conditions.

Remote Access

The remote access software works over a secured internet connection. The fast and easy access saves time in case any support or trouble shooting needs to be performed on the system. For safety reasons, nanosystec is only allowed to access the system when the user accepts. For each event, a new session is started.

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